SCLS309B - JANUARY 1996 - REVISED MAY 1997

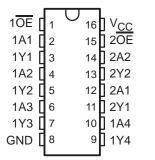
- High-Current 3-State Outputs Drive Bus Lines, Buffer Memory Address Registers, or Drive up to 15 LSTTL Loads
- True Outputs
- Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W)
   Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J)
   300-mil DIPs

### description

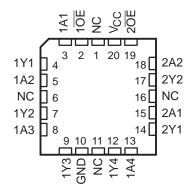
These hex buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC367 are organized as dual 4-line and 2-line buffers/drivers with active-low output-enable (1 $\overline{OE}$  and 2 $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes noninverted data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

The SN54HC367 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74HC367 is characterized for operation from –40°C to 85°C.

#### SN54HC367 . . . J OR W PACKAGE SN74HC367 . . . D OR N PACKAGE (TOP VIEW)



# SN54HC367 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

# FUNCTION TABLE (each buffer/driver)

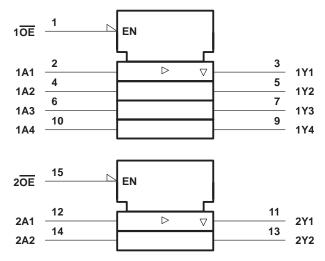
INP	JTS	OUTPUT
OE	Α	Y
Н	Χ	Z
L	Н	Н
L	L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

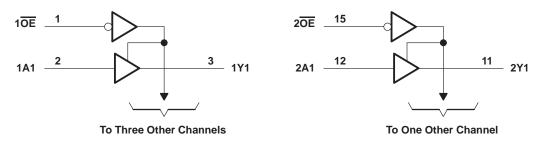


### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

### logic diagram (positive logic)



Pin numbers shown are for the D, J, N, and W packages.

## absolute maximum ratings over operating free-air temperature range‡

Supply voltage range, V <sub>CC</sub>	-0.5 \	/ to /	/ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±	±20 r	mΑ
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±	±20 r	mΑ
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±	±35 r	mΑ
Continuous current through V <sub>CC</sub> or GND	±	±70 r	mΑ
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	11	13°C	/W
N package	7	78°C	/W
Storage temperature range, T <sub>stq</sub>	65°C to	150	)°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



## recommended operating conditions

			SI	SN54HC367			174HC36	7	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII	
Vсс	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
ViH	<b>—</b>	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
	Low-level input voltage	V <sub>CC</sub> = 2 V	0		0.5	0		0.5	
VIL		V <sub>CC</sub> = 4.5 V	0		1.35	0		1.35	V
		VCC = 6 V	0		1.8	0		1.8	
٧ <sub>I</sub>	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	0		1000	0		1000	
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V	0		500	0		500	ns
		V <sub>CC</sub> = 6 V	0		400	0		400	
TA	Operating free-air temperature	-	-55		125	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		\ \ \	Т	A = 25°C	;	SN54HC367		SN74HC367		
PARAMETER			VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			8		160		80	μΑ
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

## SN54HC367, SN74HC367 HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T <sub>A</sub> = 25°C		SN54H	IC367	SN74H	C367	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		50	95		145		120		
<sup>t</sup> pd	А	Υ	4.5 V		12	19		29		24	ns	
			6 V		10	16		25		20		
			2 V		100	190		285		238		
<sup>t</sup> en	ŌĒ	Υ	Υ	4.5 V		26	38		57		48	ns
			6 V		21	32		48		41		
	<u>OE</u>	Y	2 V		50	175		265		240		
<sup>t</sup> dis			Υ	4.5 V		21	35		53		48	ns
			6 V		19	30		45		41		
		Any	2 V		28	60		90		75		
t <sub>t</sub>			Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13		

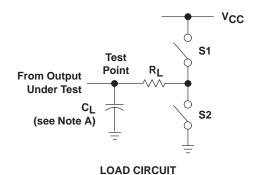
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T <sub>A</sub> = 25°C		SN54H	C367	SN74H	IC367	UNIT					
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT				
			2 V		70	120		180		150					
<sup>t</sup> pd	A	A Y	4.5 V		17	24		36		30	ns				
								6 V		14	20		31		25
		<del>OE</del> Y	2 V		140	230		345		285					
t <sub>en</sub>	ŌĒ		4.5 V		30	46		69		57	ns				
				6 V		28	39		59		48				
	Any	Any	2 V		45	210		315		265					
t <sub>t</sub>			4.5 V		17	42		63		53	ns				
				6 V		13	36		53		45				

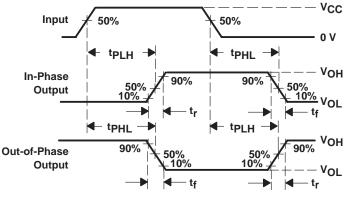
# operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per buffer/driver	No load	35	pF

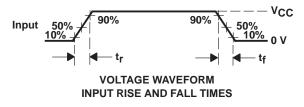
### PARAMETER MEASUREMENT INFORMATION

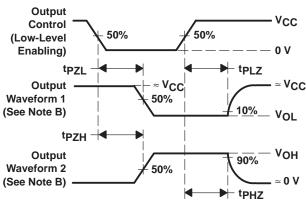


PARAI	METER	RL	CL	S1	S2
	tPZH	<b>1 k</b> Ω	50 pF or	Open	Closed
ten	tPZL	1 K22	150 pF	Closed	Open
f.u	tPHZ	1 kΩ	50 pF	Open	Closed
<sup>t</sup> dis	tPLZ	1 K22	30 pr	Closed	Open
t <sub>pd</sub> or	t <sub>pd</sub> or t <sub>t</sub>		50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES





VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ .
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - F. tpLz and tpHz are the same as tdis.
  - G. tpzL and tpzH are the same as ten.

Figure 1. Load Circuit and Voltage Waveforms



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